## **KW H3L531.TE**

#### **OSLON® Black Flat**

Oslon Black Flat is able to meet a wide range of requirements in terms of output and adaptability to ambient conditions. It offers a uniform light pattern, thermal stability and great brightness.





#### **Applications**

- Custom Tuning

- Headlamps, LED & Laser & Night Vision

#### Features:

- Package: SMD epoxy package

- Chip technology: UX:3

- Typ. Radiation: 120° (Lambertian emitter)

- Color: Cx = 0.322, Cy = 0.334 acc. to CIE 1931 (● ultra white)

— Corrosion Robustness Class: 3B

 Qualifications: The product qualification test plan is based on the guidelines of IEC60810, Lamps for road vehicles – Performance requirements – Requirements and test conditions for LED packages.

- ESD: 8 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)



Ordering Information			
Туре	Luminous Flux $^{1)}$ I <sub>F</sub> = 1000 mA $\Phi_{V}$	Ordering Code	
KW H3L531.TE-Z7Q6-ebvFfcbB46-DFYF	900 1320 lm	Q65112A4048	



Maximum Ratings			
Parameter	Symbol		Values
Operating Temperature	T <sub>op</sub>	min. max.	-40 °C 125 °C
Storage Temperature	$T_{stg}$	min. max.	-40 °C 125 °C
Junction Temperature	T <sub>j</sub>	max.	150 °C
Junction Temperature for short time applications*	T <sub>j</sub>	max.	175 °C
Forward Current T <sub>S</sub> = 25 °C	I <sub>F</sub>	min. max.	50 mA 1200 mA
Surge Current $t \le 10 \ \mu s; \ D = 0.005 \ ; \ T_s = 25 \ ^{\circ}C$	I <sub>FS</sub>	max.	2000 mA
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)	V <sub>ESD</sub>		8 kV
Reverse current 2)	I <sub>R</sub>	max.	200 mA

<sup>\*</sup>The median lifetime (L70/B50) for Tj =175 $^{\circ}$ C is 100h.

#### **KW H3L531.TE**

## **Characteristics**

 $I_F$  = 1000 mA;  $T_S$  = 25 °C

Parameter	Symbol		Values
Chromaticity Coordinate 3)	Сх	typ.	0.322
	Су	typ.	0.334
Viewing angle at 50 $\%~{\rm I_v}$	2φ	typ.	120 °
Radiating surface	$A_{color}$	typ.	3.3 mm <sup>2</sup>
Forward Voltage 4)	$V_{F}$	min.	8.15 V
I <sub>F</sub> = 1000 mA	•	typ.	9.20 V
		max.	11.15 V
Reverse voltage (ESD device)	V <sub>R ESD</sub>	min.	45 V
Reverse voltage <sup>2)</sup> I <sub>R</sub> = 20 mA	$V_R$	max.	1.2 V
Real thermal resistance junction/solderpoint 5)	R <sub>thJS real</sub>	typ.	1.30 K / W
	thooreal	max.	1.60 K / W
Electrical thermal resistance junction/solderpoint 5)	$R_{ ext{thJS elec.}}$	typ.	0.91 K / W
with efficiency $\eta_e$ = 30 %	and died.	max.	1.12 K / W



# **Brightness Groups**

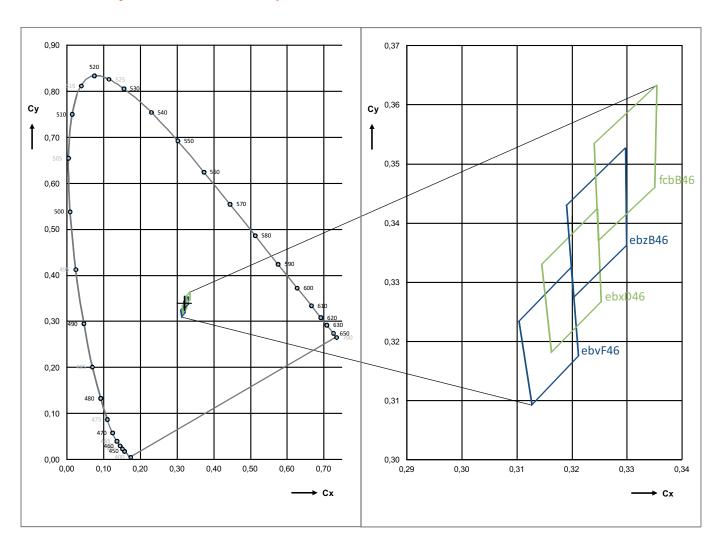
Group	Luminous Flux <sup>1)</sup> $I_F = 1000 \text{ mA}$ min. $\Phi_V$	Luminous Flux <sup>1)</sup> $I_F = 1000 \text{ mA}$ max. $\Phi_V$	Luminous Intensity $^{6)}$ $I_F = 1000 \text{ mA}$ typ. $I_V$	
7Q	900 lm	1000 lm	314 cd	_
7QF	949 lm	1060 lm	332 cd	
8Q	1000 lm	1120 lm	350 cd	
8QF	1060 lm	1180 lm	370 cd	
5R	1120 lm	1250 lm	391 cd	
5RF	1180 lm	1320 lm	413 cd	

# **Forward Voltage Groups**

Group	Forward Voltage <sup>4)</sup> I <sub>F</sub> = 1000 mA min. V <sub>F</sub>	Forward Voltage <sup>4)</sup> I <sub>F</sub> = 1000 mA max. V <sub>F</sub>	
DF	8.15 V	8.90 V	
UF	8.90 V	9.65 V	
GF	9.65 V	10.40 V	
YF	10.40 V	11.15 V	



# **Chromaticity Coordinate Groups** 3)



# Color Chromaticity Groups 3)

Group	Cx	Су		Group	Cx	Су
ebvF46	0.3127	0.3093	ebzB46		0.3203	0.3274
	0.3212	0.3175			0.3299	0.3361
	0.3199	0.3325			0.3298	0.3526
	0.3104	0.3234			0.3190	0.3430
ebxD46	0.3163	0.3181		fcbB46	0.3248	0.3370
	0.3253	0.3266			0.3350	0.3460
	0.3246	0.3424			0.3355	0.3633
	0.3145	0.3330			0.3241	0.3534



## **Group Name on Label**

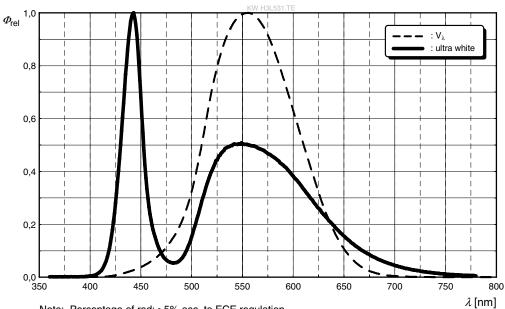
Example: 5R-ebvF46-DF

Brightness	Color chromaticity	Forward Voltage
5R	ebvF46	DF



## Relative Spectral Emission 6)

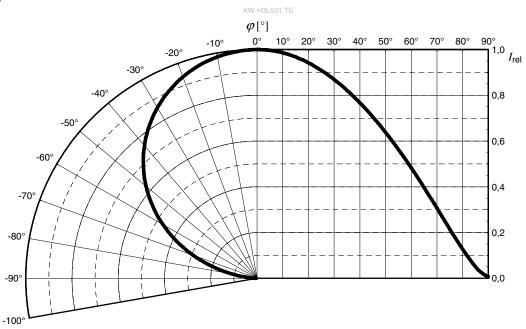
 $\Phi_{rel}$  = f ( $\lambda$ ); I<sub>F</sub> = 1000 mA; T<sub>S</sub> = 25 °C



Note: Percentage of red: >5% acc. to ECE regulation Percentage of UV: <10-5 W/lm acc. to ECE regulation

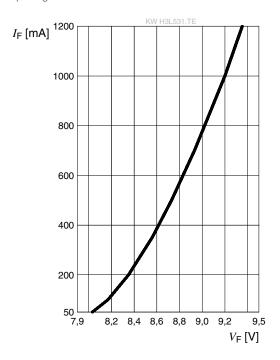
#### Radiation Characteristics 6)

 $I_{rel} = f (\phi); T_S = 25 °C$ 



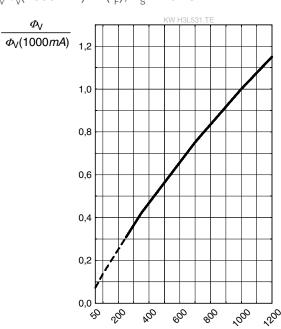
### Forward current 6), 7)

$$I_F = f(V_F); T_S = 25 \, ^{\circ}C$$



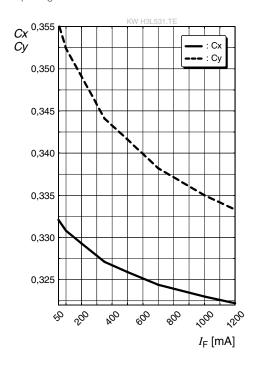
### Relative Luminous Flux 6), 7)

$$\Phi_{V}/\Phi_{V}(1000 \text{ mA}) = f(I_{F}); T_{S} = 25 \text{ }^{\circ}\text{C}$$



## **Chromaticity Coordinate Shift** 6)

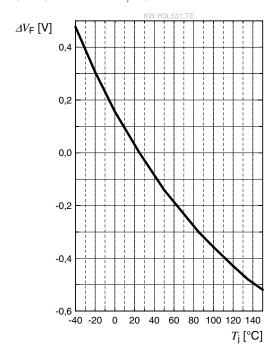
$$Cx,Cy = f(I_F); T_S = 25^{\circ}C$$



 $I_{\mathsf{F}}\left[\mathsf{mA}\right]$ 

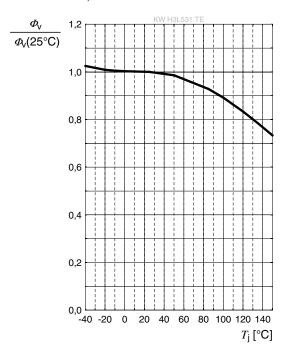
### Forward Voltage 6)

$$\Delta V_F = V_F - V_F (25 \text{ °C}) = f(T_j); I_F = 1000 \text{ mA}$$



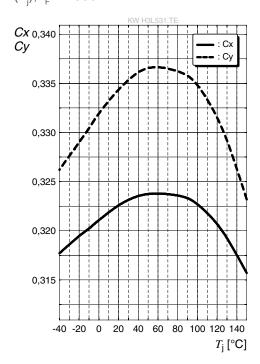
#### Relative Luminous Flux 6)

$$\Phi_{v}/\Phi_{v}(25 \text{ °C}) = f(T_{i}); I_{F} = 1000 \text{ mA}$$



## **Chromaticity Coordinate Shift** 6)

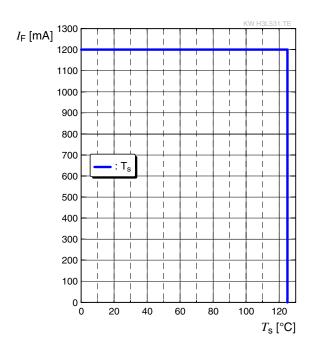
$$Cx,Cy = f(T_i); I_F = 1000 \text{ mA}$$





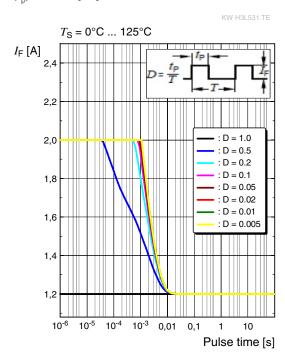
## Max. Permissible Forward Current

 $I_F = f(T); 0.7 * \Phi_{V \text{ min.}} \text{ of bin 7Q}; R_{th \text{ real max.}}$ 



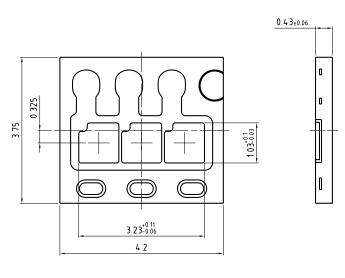
## **Permissible Pulse Handling Capability**

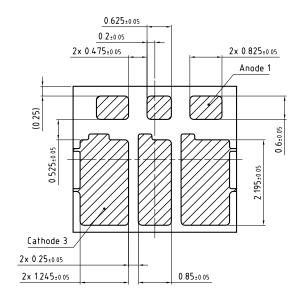
 $I_F = f(t_0)$ ; D: Duty cycle





### **Dimensional Drawing** 8)





Lead finish Au

genaral tolerance ±0.1

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**Approximate Weight:** 22.0 mg

Corrosion test: Class: 3B

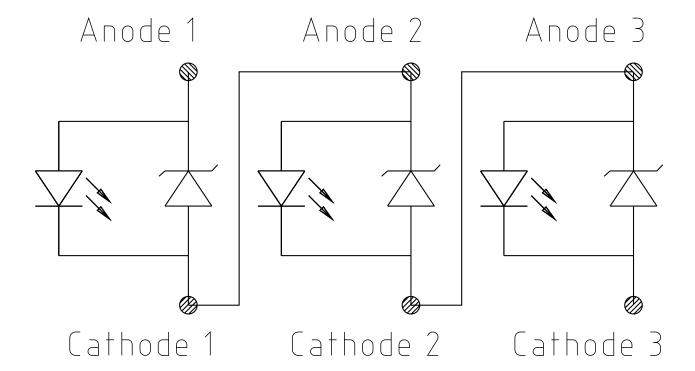
Test condition:  $40^{\circ}$ C / 90 % RH / 15 ppm  $H_2$ S / 14 days (stricter then IEC

60068-2-43)

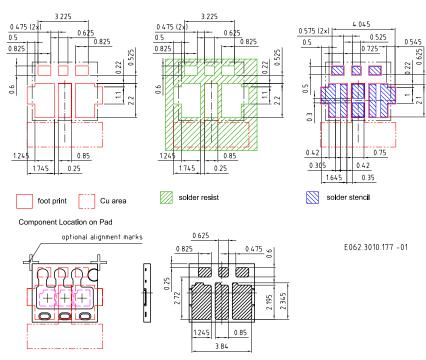
**ESD advice:** The device is protected by ESD device which is connected in parallel to the

Chip.

### **Electrical internal circuit**



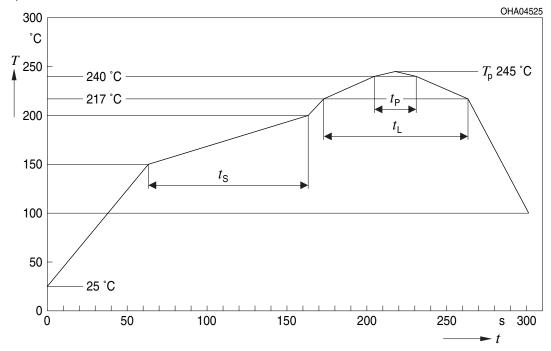
### Recommended Solder Pad 8)



For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.

### **Reflow Soldering Profile**

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



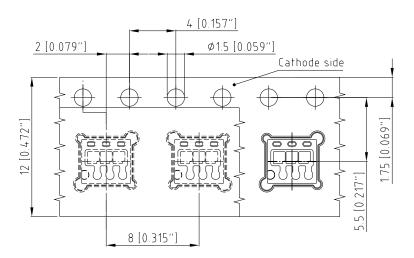
Profile Feature	Symbol	Pb	sembly	Unit	
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time $t_s$ $T_{Smin}$ to $T_{Smax}$	t <sub>s</sub>	60	100	120	S
Ramp-up rate to peak*) $T_{\rm Smax}$ to $T_{\rm P}$			2	3	K/s
Liquidus temperature	$T_L$		217		°C
Time above liquidus temperature	$t_{\scriptscriptstyle \perp}$		80	100	S
Peak temperature	T <sub>P</sub>		245	260	°C
Time within 5 °C of the specified peak temperature T <sub>p</sub> - 5 K	t <sub>P</sub>	10	20	30	S
Ramp-down rate* T <sub>P</sub> to 100 °C			3	6	K/s
Time 25 °C to T <sub>P</sub>				480	S

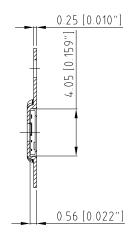
All temperatures refer to the center of the package, measured on the top of the component  $^{\star}$  slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range



# Taping 8)

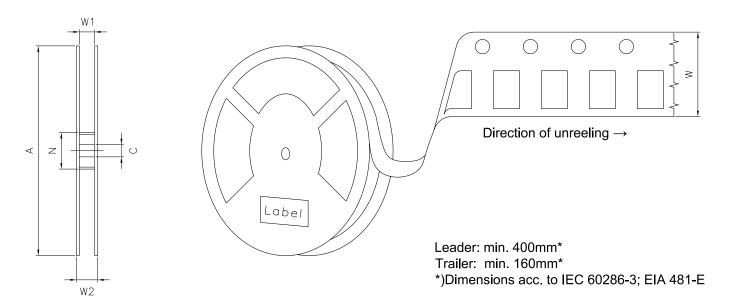






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## Tape and Reel 9)



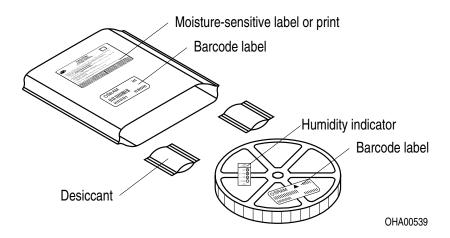
# Reel dimensions [mm]

A	W	$N_{\min}$	W <sub>1</sub>	$W_{2max}$	Pieces per PU
180 mm	12 + 0.3 / - 0.1	60	12.4 + 2	18.4	2000

# **Barcode-Product-Label (BPL)**



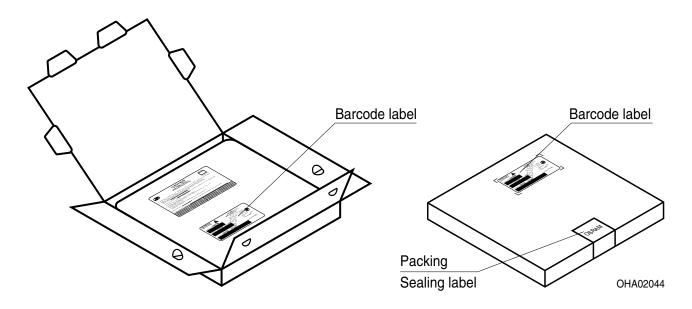
## **Dry Packing Process and Materials 8)**



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



# Transportation Packing and Materials 8)



# Dimensions of transportation box in mm

Width	Length	Height
195 ± 5 mm	195 ± 5 mm	30 ± 5 mm



# **Type Designation System**

	Wavelength (λ <sub>dom</sub> typ.)	Emission Co		coordina 331/Emis					
	A: 617 nm S: 633 nm Y: 587 nm R: 625 nm	n super red n yellow	CY: UW: W:	color on ultra whit white		yellow			
	K: Automotiv and Indus Product	stry /	3: S (0	ogy Con llicone en casted) latform: C	capsula	tion			
	L: Light emitting diode	H: Top Lea	kage Type emitting device adframe based ector package	d, <u>Black</u>		Proc vers	duct sion		
	KW	н	2 L	5	3	1		Т	E
J: K: 2: 3: 4: 5: Lead J: K:	100ker: 1010 0808 3137 4237 5337 6437 dframe 5737 6837 7937	Sidelooker: J: 4206  PCB: K: 5050 L: 5555  Ceramic packages 2: 3538 3: 4638			T:	green	nish colo	d white	
9: W:	Standard Ce keep free for apsulant Type No lens (Lam planar compi (120°); with v planar compi	/ Lens Properties			E:	ECE		IEC 627	07
	<b>Chip</b> 5:	Technology: Standard power cla power performance							

#### **Notes**

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet falls into the class moderate risk (exposure time 0.25 s). Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this LED contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize LED exposure to aggressive substances during storage, production, and use. LEDs that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related informations please visit www.osram-os.com/appnotes



#### **Disclaimer**

#### Disclaimer

Language english will prevail in case of any discrepancies or deviations between the two language wordings.

#### Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS webside.

#### **Packing**

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office

By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

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OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

In case Buyer – or Customer supplied by Buyer– considers using OSRAM OS components in product safety devices/applications or medical devices/applications, Buyer and/or Customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and Buyer and /or Customer will analyze and coordinate the customer-specific request between OSRAM OS and Buyer and/or Customer.



#### Glossary

- Brightness: Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of ±8 % and an expanded uncertainty of ±11 % (acc. to GUM with a coverage factor of
- Reverse Operation: Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.
- 3) Chromaticity coordinate groups: Chromaticity coordinates are measured during a current pulse of typically 25 ms, with an internal reproducibility of ±0.005 and an expanded uncertainty of ±0.01 (acc. to GUM with a coverage factor of k = 3).
- Forward Voltage: The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ±0.05 V and an expanded uncertainty of ±0.1 V (acc. to GUM with a coverage factor of k = 3).
- 5) Thermal Resistance: Rth max is based on statistic values (60).
- 6) Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- Characteristic curve: In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- Tape and Reel: All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



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